QFP Desoldering

* Plug the power cord into the power supply.

After connection, the automatic blowing function may start sending air through the pipe, but the Heating Element remains cool.

* Turn the Power switch on.

The Power Switch may be turned on at any time while the automatic blowing function, is operating. Once the Power Switch is turned on, the Heating Element will begin to warm up.

* Adjust the Air Flow and Temperature Control Knobs.

After adjusting the Air flow and Temperature Control Knob, wait for the temperature to stabilize for a short period of time. Refer to the distribution chart. For your reference, we recommend you to adjust the temperature around 300 to 350°C. As for Air Flow in case of single nozzle, set the knob 1-5, in another nozzle, set it from 4-7. when the working temperature is over 450°C, the knob of airflow control must be over 4 position.

* Place the FP Pick-up under IC lead.

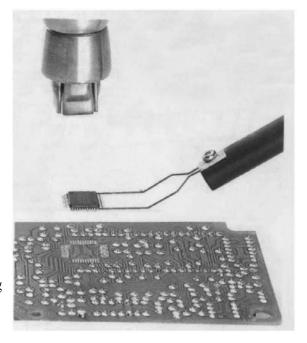
Slip the FP Pick-up Wire under the IC lead. If the width of the IC does not match the size Of the FP Pick-up, adjust the width of the wire By suppressing the wire.

* Melt the solder

Hold the iron so that the Nozzle is located directly Over, but not touching the IC, and allow the hot air To melt the solder. Be careful not to touch the leads Of the IC with the nozzle.

* Remove the IC.

Once the solder has melted, remove the IC by lifting The FP Pick-up.



* Turn the Power Switch off.

In case you don't use the unit for a long time, disconnect the plug.

* Remove any remaining solder.

After removing the IC, remove remaining solder with a wick or desoldering tool. Note: in case of SOP, PLCC desolder it by using tweezers, etc.

QFP Soldering

* Apply the solder paste.

Apply the proper quantity of solder paste and install the SMD on the PWB.

* Preheat SMD.

Refer to the photo to preheat SMD. (Fig. I)

* Soldering

Heat the lead frame evenly. (Fig. II)

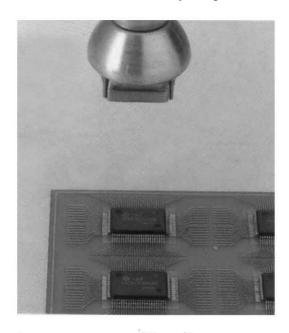


Fig. I

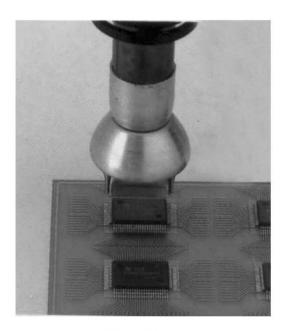


Fig. I

* Washing

When soldering is completed. Wash away the flux.

Note: While there is merits to solder by Hot air, it's also possible

To cause the defects such as solder balls, solder bridges. We recommend you to examine the conditions of soldering sufficiently.